



Product Change Notification

Change Notification #: 115791 - 00
Change Title: Intel® Integrated RAID Module
RMS3AC160,
PCN 115791-00, Product Design, Product
Material
Stand-offs, Firmware and CPLD Code
Upgrades
Date of Publication: September 1, 2017

Key Characteristics of the Change:

Product Design, Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	Sep 1, 2017
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following change on the Intel® RAID Module RMS3AC160:

- Upgrade the controller's firmware to package version 24.19.0-0047 (MR 6.13) and upgrade the CPLD (Complex Programmable Logic Device) code.
- Upgrade the stand-offs which include a pull tab for easier removal.

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from this change. Customers may need to validate the function and feature change once the post-change system is available.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
RMS3AC160	947032	H86846-002	H86847-201	H86846-003	H86847-202

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
September 1, 2017	00	Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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